

Notification Number:	20220817000.0	Notification Date:	August 17, 2022
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Title:	Datasheet for SN74AUC1G125		
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Customer Contact:	PCN Manager	Dept:	Quality Services
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Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



SN74AUC1G125

SCES382M – MARCH 2002 – REVISED AUGUST 2022

Changes from Revision L (June 2017) to Revision M (August 2022)	Page
• Updated the numbering format for tables, figures, and cross-references throughout the document	1
• Updated the <i>Features</i> section, <i>Applications</i> section, and <i>Device Information</i> table.....	1
• Changed the YZP (DSBGA, 5) body size from: 1.75 mm × 1.25 mm to: 1.39 mm × 0.89 mm	1
• Added the <i>Application and Implementation</i> , <i>Application Information</i> , <i>Typical Application</i> , <i>Power Supply Recommendations</i> , <i>Layout</i> , <i>Layout Guidelines</i> , and <i>Layout Examples</i> sections.....	1
• Updated the <i>Pin Configuration and Functions</i> section.....	3
• Updated the <i>ESD Ratings</i> section.....	4
• Updated the <i>Thermal Information</i> section.....	5

The datasheet number will be changing.

Device Family	Change From:	Change To:
SN74AUC1G125	SCES382L	SCES382M

These changes may be reviewed at the datasheet links provided.

<https://www.ti.com/product/SN74AUC1G125>

Error! Bookmark not defined.

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this notification:

None.

Product Affected:

74AUC1G125DBVRE4	74AUC1G125DBVRG4	74AUC1G125DCKRE4	74AUC1G125DCKRG4
SN74AUC1G125DBVR	SN74AUC1G125DCKR	SN74AUC1G125YZPR	

For questions regarding this notice, e-mails can be sent to the contact shown below or your local Field Sales Representative.

Location	E-Mail
WW PCN Team	PCN_ww_admin_team@list.ti.com

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